
GLOSSARY OF TECHNICAL TERMS

"AI"	artificial intelligence
"AIDC"	AI data centers
"ASIC"	application-specific integrated circuit
"BUCK" control	an efficient electronic circuit that steps down a higher DC input voltage to a lower DC output voltage, using rapid switching, an inductor, and a capacitor
"CAGR"	compound annual growth rate
"CCC"	China Compulsory Certification for products entering China
"CE"	Conformité Européenne (European Conformity), is a mandatory certification indicating a product meets European Union (EU) health, safety, and environmental standards
"CRPS"	Common Redundant Power Supply
"CSR"	corporate social responsibility
"CQC"	a voluntary product quality mark primarily from the China Quality Certification Centre indicating compliance with Chinese safety, performance, and environmental standards
"DC/AC"	direct current/alternating current
"DC/DC"	direct current to direct current
"Delta Group"	Delta Electronics, Inc. and its subsidiaries
"DIP"	dual in-line package
"EFLOPS"	Exa Floating-point Operations Per Second
"EMC"	electromagnetic compatibility
"EMI"	electromagnetic interference

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"ESD"	electrostatic discharge
"ESG"	environmental, social, and governance
"ESS"	energy storage solution
"EV"	electric vehicle
"GaN"	gallium nitride
"GB2828.1"	a Chinese National Standard for sampling procedures for inspection by attributes, specifically Part 1, which outlines sampling schemes indexed by Acceptance Quality Limit (AQL) for lot-by-lot inspection
"GHG"	greenhouse gas
"GPU"	graphics processing unit
"HiPot"	high potential test
"HPC"	high-performance computing
"HVDC"	high-voltage direct current
"IFRS"	International Financial Reporting Standards
"IP65"	an Ingress Protection (IP) rating meaning an enclosure is dust-tight (6) and protected against low-pressure water jets from any direction (5), making it ideal for outdoor use or environments with cleaning spray, but not for full submersion
"IPC-A-600K"	the "K" revision of the IPC-A-600 standard for Acceptability of Printed Boards, that describes the target, acceptable, and nonconforming conditions that are either externally or internally observable on printed boards
"IPC-JEDEC-J-STD-033C"	a joint industry standard that provides guidelines for the handling, packing, shipping, and use of moisture/reflow sensitive surface-mount devices (SMDs)

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"ISO9001"	the globally recognized standard for Quality Management Systems (QMS)
"ISO14001"	the international standard for an Environmental Management System (EMS)
"ISO45001"	the international standard for Occupational Health and Safety (OH&S) Management Systems
"IATF16949"	the international quality management system (QMS) standard for the automotive industry
"KPI"	key performance indicator
"kW"	a unit of power, measuring the rate at which electrical energy is used or generated, equivalent to 1,000 watts
"Lead Protrusion"	the part of a component's wire or pin that extends beyond its intended surface, often seen in electronics after soldering, where it's crucial for good electrical and mechanical connection but must stay within specific length limits (e.g., IPC standards) to prevent shorts or damage.
"kW"	kilowatt
"LLC"	inductor-inductor-capacitor
"Molten Solder Wave"	a continuously moving, undulating stream of liquid solder used in electronics manufacturing to quickly and reliably join components, especially through-hole parts, to a circuit board
"MPPT"	maximum power point tracking
"MSDS"	material safety data sheet
"MW"	megawatt
"MWh"	megawatt-hour
"NPI"	new product introduction

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“OEM”	original equipment manufacturer
“OCP”	open compute project
“OTA”	Over-the-Air, the method of delivering data, software, firmware, or configuration updates wirelessly, without requiring a physical connection or manual intervention.
“PCB”	printed circuit board
“PCS”	power conversion system
“PFC”	power factor correction
“PRC”	People’s Republic of China
“PV”	photovoltaic
“QC08000”	the international technical specification (standard) for a Hazardous Substance Process Management (HSPM) system in the electrical and electronic components and products industry
“R&D”	research and development
“SiC”	silicon carbide
“SMT”	surface mount technology
“Solder Fillet”	the smooth, curved, concave (or sometimes slightly convex) formation of solder at the junction where a component lead meets a printed circuit board (PCB) pad
“TISAX”	Trusted Information Security Assessment Exchange
“TMT”	Technology, media, and telecommunications
“Transient Response Latency”	the time delay between a sudden input change (like a voltage step or load shift) and when a system’s output stabilizes to its new, steady-state level, measuring how quickly the system recovers

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“UAV”	unmanned aerial vehicle
“UL”	UL certification, from Underwriters Laboratories (UL) Solutions, means a product has been independently tested and verified to meet specific safety and performance standards
“UPS”	uninterruptable power supply
“V”	Volt(s)
“W”	Watt(s)
“W/in ³ ”	a unit of power density, measuring how much power (in Watts) can fit into a specific volume (one cubic inch)